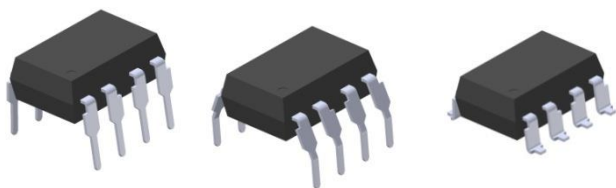


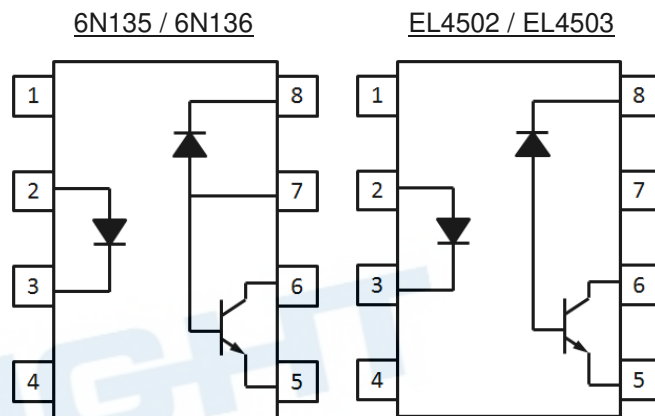
### 8 PIN DIP HIGH SPEED 1Mbit/s TRANSISTOR PHOTOCOUPLER 6N135 6N136 EL450X Series



#### Features

- High speed 1Mbit/s
- High isolation voltage between input and output (Viso=5000 Vrms )
- Guaranteed performance from 0°C to 70°C
- Wide operating temperature range of -55°C to 100°C
- Pb free and RoHS compliant
- UL and cUL approved(No. E214129)
- VDE approved (No. 132249)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved

#### Schematic



#### Pin Configuration

1. No Connection
2. Anode
3. Cathode
4. No Connection
5. Gnd
6.  $V_{out}$
7.  $V_B$
8.  $V_{CC}$

#### Pin Configuration

1. No Connection
2. Anode
3. Cathode
4. No Connection
5. Gnd
6.  $V_{out}$
7. No Connection
8.  $V_{CC}$

#### Description

The 6N135, 6N136, EL4502 and EL4503 devices each consist of an infrared emitting diode, optically coupled to a high speed photo detector transistor. A separate connection for the photodiode bias and output-transistor collector increase the speed by several orders of magnitude over conventional phototransistor couplers by reducing the base-collector capacitance of the input transistor. The devices are packaged in an 8-pin DIP package and available in wide-lead spacing and SMD option

#### Applications

- Line receivers
- Telecommunication equipments
- Power transistor isolation in motor drives
- Replacement for low speed phototransistor photo couplers
- Feedback loop in switch-mode power supplies
- Home appliances
- High speed logic ground isolation

**Absolute Maximum Ratings (Ta=25°C)**

Parameter		Symbol	Rating	Unit
Input	Forward current	$I_F$	25	mA
	Peak forward current (50% duty, 1ms P.W)	$I_{FP}$	50	mA
	Peak transient current ( $\leq 1\mu s$ P.W, 300pps)	$I_{Ftrans}$	1	A
	Reverse voltage	$V_R$	5	V
	Power dissipation	$P_{IN}$	45	mW
Output	Power dissipation	$P_O$	100	mW
	Emitter-Base reverse voltage	6N135 6N136 $V_{EBR}$	5	V
	Base current	6N135 6N136 $I_B$	5	mA
	Average Output current	$I_{O(AVG)}$	8	mA
	Peak Output current	$I_{O(PK)}$	16	mA
	Output voltage	$V_O$	-0.5 to 20	V
	Supply voltage	$V_{CC}$	-0.5 to 30	V
Total Power Dissipation		$P_{TOT}$	200	mW
Isolation Voltage*1		$V_{ISO}$	5000	Vrms
Operating Temperature		$T_{OPR}$	-55 to 100	°C
Storage Temperature		$T_{STG}$	-55 to 125	°C
Soldering Temperature*2		$T_{SOL}$	260	°C

**Notes:**

\*1 AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2, 3, 4 are shorted together, and pins 5, 6, 7, 8 are shorted together.

\*2 For 10 seconds

**Electrical Characteristics (T<sub>A</sub>=0 to 70°C unless specified otherwise)****Input**

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward Voltage	V <sub>F</sub>	-	1.45	1.8	V	I <sub>F</sub> = 16mA
Reverse Voltage	V <sub>R</sub>	5.0	-	-	V	I <sub>R</sub> = 10μA
Temperature coefficient of forward voltage	ΔV <sub>F</sub> /ΔT <sub>A</sub>	-	-1.9	-	mV/°C	I <sub>F</sub> = 16mA

**Output**

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Logic High Output Current	I <sub>OH</sub>	-	0.001	0.5	μA	I <sub>F</sub> =0mA, V <sub>O</sub> =V <sub>CC</sub> =5.5V, T <sub>A</sub> =25°C
		-	0.01	1		I <sub>F</sub> =0mA, V <sub>O</sub> =V <sub>CC</sub> =15V, T <sub>A</sub> =25°C
		-	-	50		I <sub>F</sub> =0mA, V <sub>O</sub> =V <sub>CC</sub> =15V
Logic Low Supply Current	I <sub>CCL</sub>	-	140	200	μA	I <sub>F</sub> =16mA, V <sub>O</sub> =Open, V <sub>CC</sub> =15V
Logic High Supply Current	I <sub>CCH</sub>	-	0.01	1	μA	I <sub>F</sub> =0mA, V <sub>O</sub> =Open, V <sub>CC</sub> =15V, T <sub>A</sub> =25°C
		-	-	2		I <sub>F</sub> =0mA, V <sub>O</sub> =Open, V <sub>CC</sub> =15V

**Transfer Characteristics (T<sub>A</sub>=0 to 70°C unless specified otherwise)**

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition	
Current Transfer Ratio	6N135	7	-	50	%	$I_F = 16\text{mA}$ , $V_O = 0.4\text{V}$ , $V_{CC}=4.5\text{V}$ , $T_A=25^\circ\text{C}$	
	6N136	19	-	50			
	EL4502 EL4503						
	6N135	5	-	-		$I_F = 16\text{mA}$ , $V_O = 0.5\text{V}$ , $V_{CC}=4.5\text{V}$	
	6N136	15	-	-			
	EL4502 EL4503						
Logic Low Output Voltage	6N135	-	0.18	0.4	V	$I_F = 16\text{mA}$ , $I_O = 1.1\text{mA}$ , $V_{CC}=4.5\text{V}$ , $T_A=25^\circ\text{C}$	
	6N136	-	0.25	0.4		$I_F = 16\text{mA}$ , $I_O = 3\text{mA}$ , $V_{CC}=4.5\text{V}$ , $T_A=25^\circ\text{C}$	
	EL4502 EL4503						
	6N135	-	-	0.5		$I_F = 16\text{mA}$ , $I_O = 0.8\text{mA}$ , $V_{CC}=4.5\text{V}$	
	6N136	-	-	0.5		$I_F = 16\text{mA}$ , $I_O = 2.4\text{mA}$ , $V_{CC}=4.5\text{V}$	
	EL4502 EL4503						

**Switching Characteristics ( $T_A=0$  to  $70^\circ\text{C}$  unless specified otherwise,  $I_F=16\text{mA}$ ,  $V_{CC}=5\text{V}$ )**

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Propagation Delay Time to Logic Low (Fig.8)	6N135	-	0.35	1.5	$\mu\text{s}$	$R_L=4.1\text{K}\Omega$ , $T_A=25^\circ\text{C}$
		-	-	2.0		$R_L=4.1\text{K}\Omega$
	6N136 EL4502 EL4503	-	0.35	0.8		$R_L=1.9\text{K}\Omega$ , $T_A=25^\circ\text{C}$
		-	-	1.0		$R_L=1.9\text{K}\Omega$
Propagation Delay Time to Logic High (Fig.8)	6N135	-	0.5	1.5	$\mu\text{s}$	$R_L=4.1\text{K}\Omega$ , $T_A=25^\circ\text{C}$
		-	-	2.0		$R_L=4.1\text{K}\Omega$
	6N136 EL4502 EL4503	-	0.3	0.8		$R_L=1.9\text{K}\Omega$ , $T_A=25^\circ\text{C}$
		-	-	1.0		$R_L=1.9\text{K}\Omega$
Common Mode Transient Immunity at Logic High (Fig.9)*3	6N135	1,000	-	-	$\text{V}/\mu\text{s}$	$I_F=0\text{mA}$ , $V_{CM}=10\text{Vp-p}$ , $R_L=4.1\text{K}\Omega$ , $T_A=25^\circ\text{C}$
	6N136 EL4502	1,000	-	-		$I_F=0\text{mA}$ , $V_{CM}=10\text{Vp-p}$ , $R_L=1.9\text{K}\Omega$ , $T_A=25^\circ\text{C}$
	EL4503	15000	20000	-		$I_F=0\text{mA}$ , $V_{CM}=1500\text{Vp-p}$ , $R_L=1.9\text{K}\Omega$ , $T_A=25^\circ\text{C}$
Common Mode Transient Immunity at Logic Low (Fig.9)*3	6N135	1,000	-	-	$\text{V}/\mu\text{s}$	$I_F=16\text{mA}$ , $V_{CM}=10\text{Vp-p}$ , $R_L=4.1\text{K}\Omega$ , $T_A=25^\circ\text{C}$
	6N136 EL4502	1,000	-	-		$I_F=16\text{mA}$ , $V_{CM}=10\text{Vp-p}$ , $R_L=1.9\text{K}\Omega$ , $T_A=25^\circ\text{C}$
	EL4503	15000	20000	-		$I_F=16\text{mA}$ , $V_{CM}=1500\text{Vp-p}$ , $R_L=1.9\text{K}\Omega$ , $T_A=25^\circ\text{C}$

\* Typical values at  $T_A=25^\circ\text{C}$

# Typical Electro-Optical Characteristics Curves

Fig.1 Forward Current vs. Forward Voltage

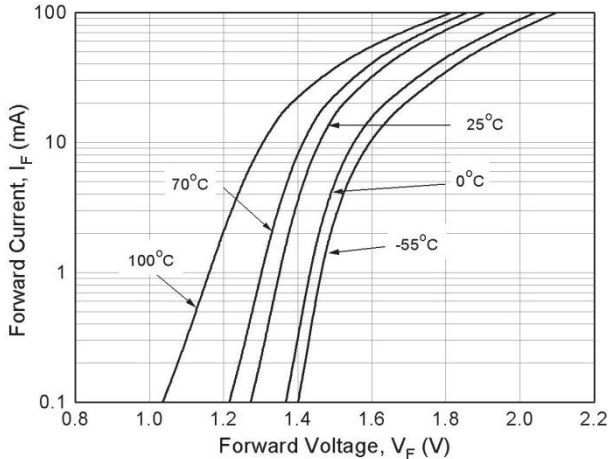


Fig.2 Normalized Current Transfer Ratio vs. Forward Current

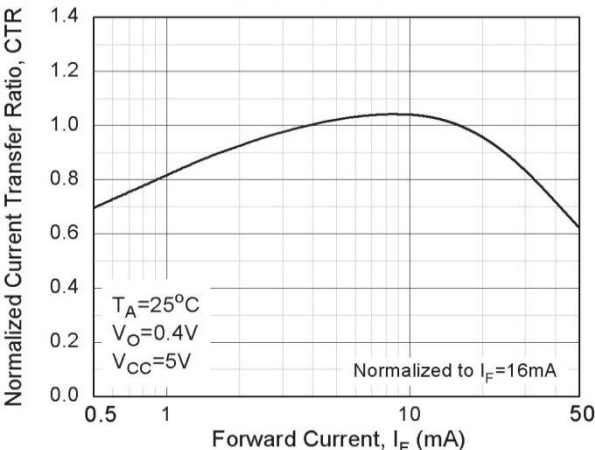


Fig.3 Normalized Current Transfer Ratio vs. Ambient Temperature

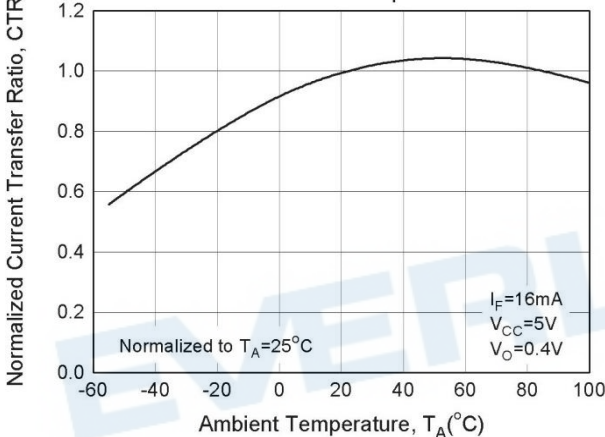


Fig.4 Output Current vs Output Voltage

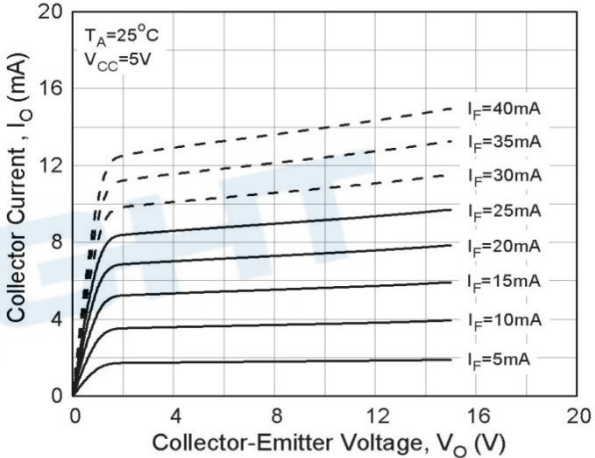


Fig.5 Logic High Output Current vs. Temperature

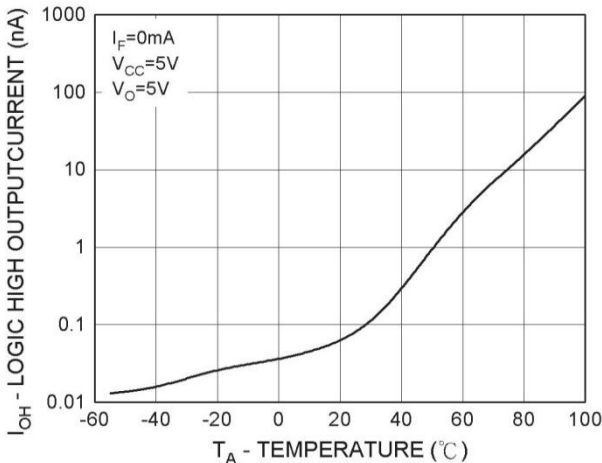


Fig.6 Propagation Delay vs. Load Resistance

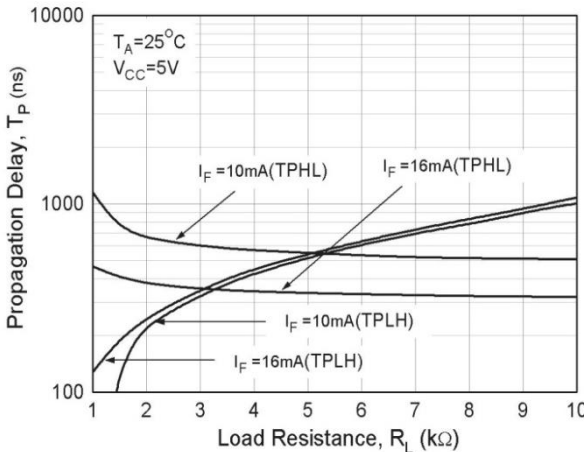


Fig.7 Propagation Delay vs. Temperature

## Order Information

### Part Number

**6N13XY(Z)-V**

or

**EL450XY(Z)-V**

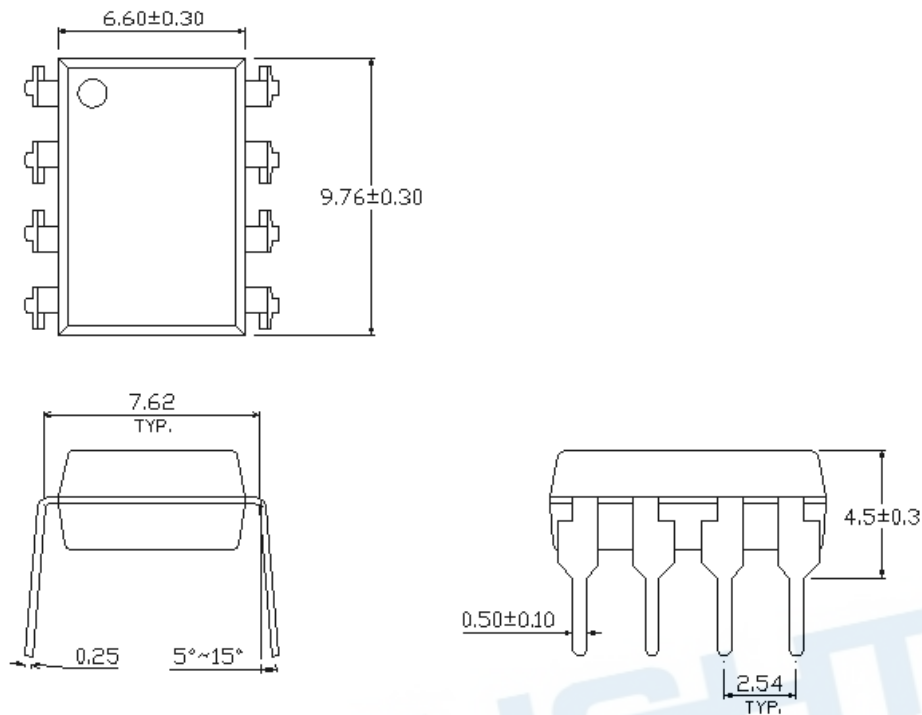
### Note

- X = Part No. (X = 5 or 6) for 6N series; (X=2 or 3) for EL45 series  
Y = Lead form option (S, S1, M or none)  
Z = Tape and reel option (TA, TB or none)  
V = VDE (optional)

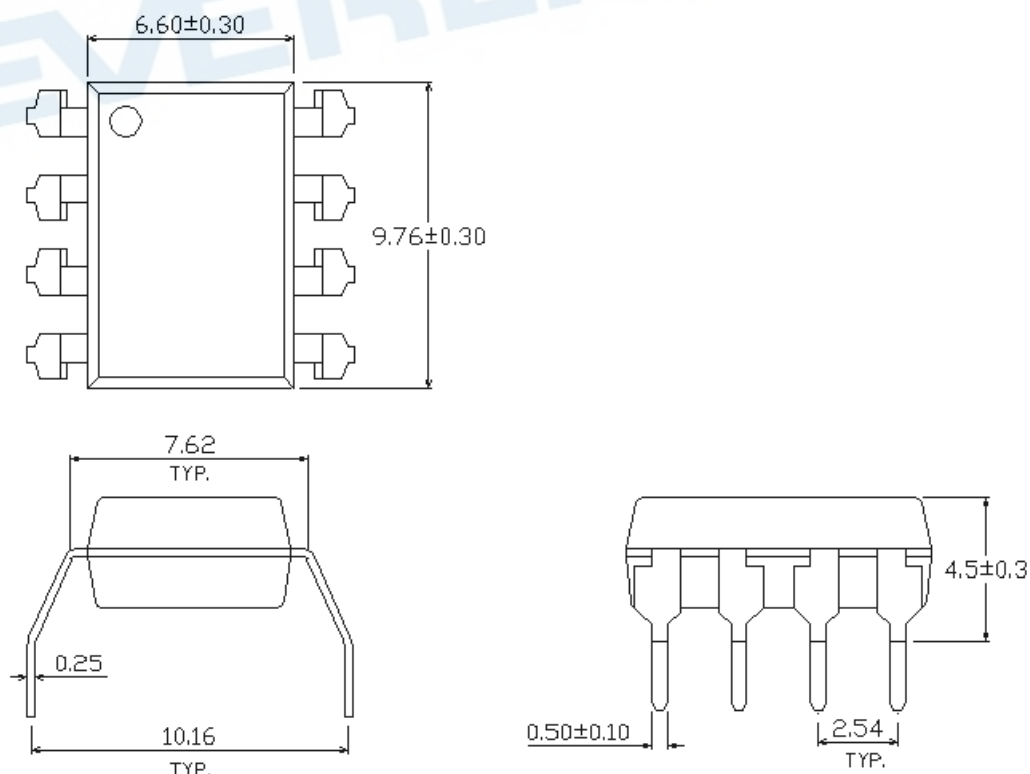
Option	Description	Packing quantity
None	Standard DIP-8	45 units per tube
M	Wide lead bend (0.4 inch spacing)	45 units per tube
S (TA)	Surface mount lead form + TA tape & reel option	1000 units per reel
S (TB)	Surface mount lead form + TB tape & reel option	1000 units per reel
S1 (TA)	Surface mount lead form (low profile) + TA tape & reel option	1000 units per reel
S1 (TB)	Surface mount lead form (low profile) + TB tape & reel option	1000 units per reel

## Package Dimension (Dimensions in mm)

### Standard DIP Type

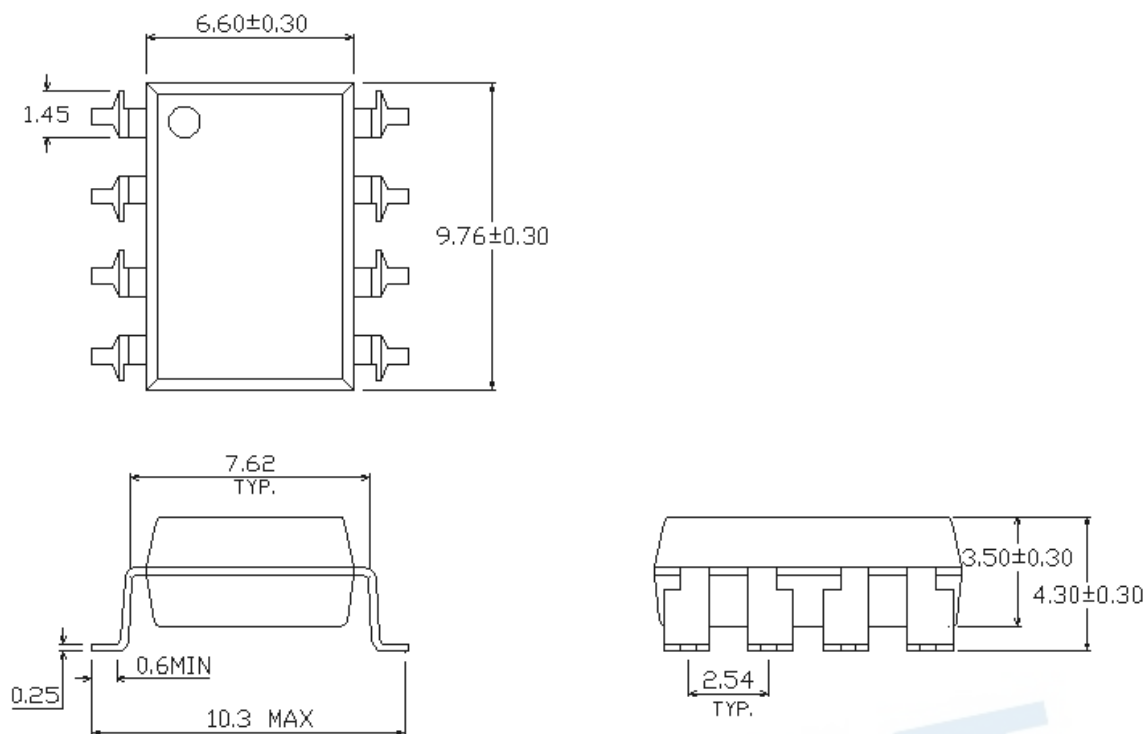


### Option M Type

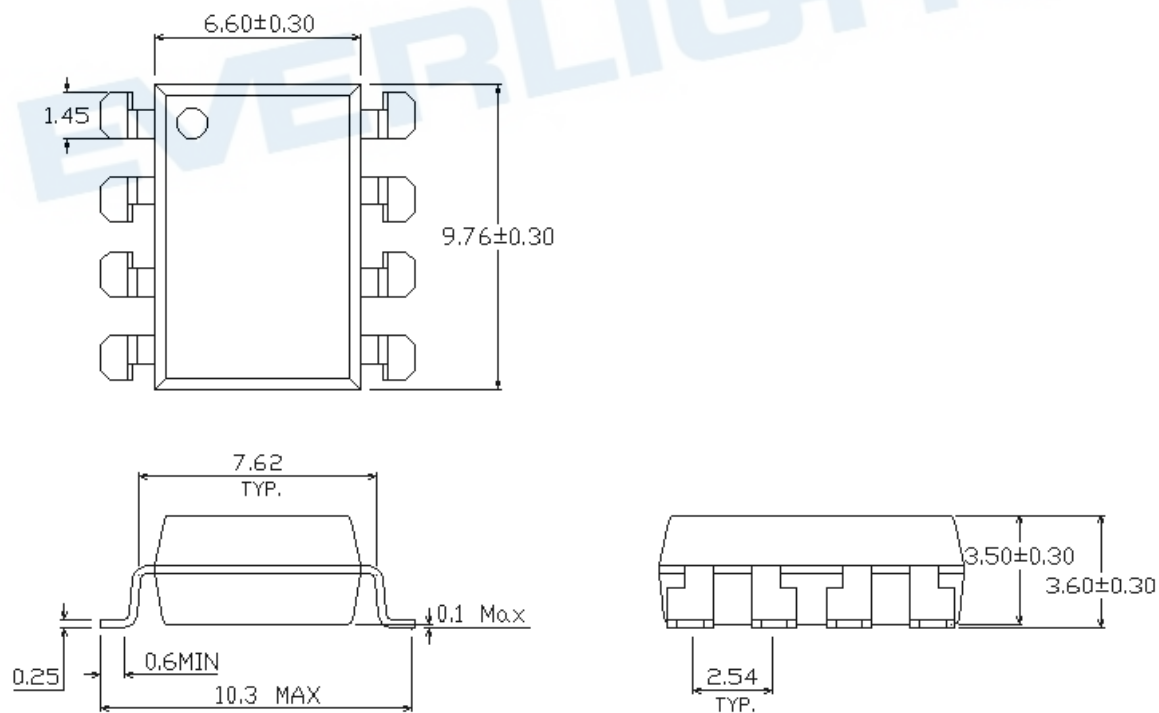




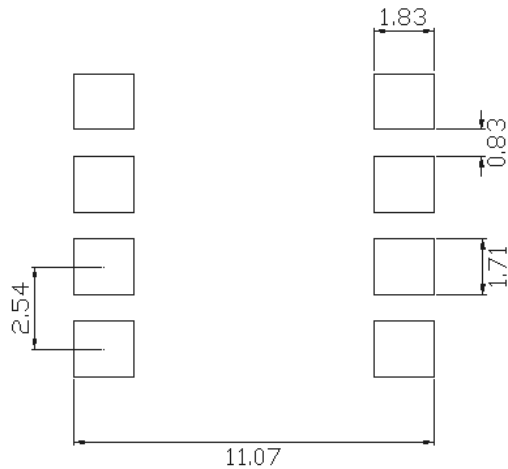
## Option S Type



## Option S1 Type



## Recommended pad layout for surface mount leadform

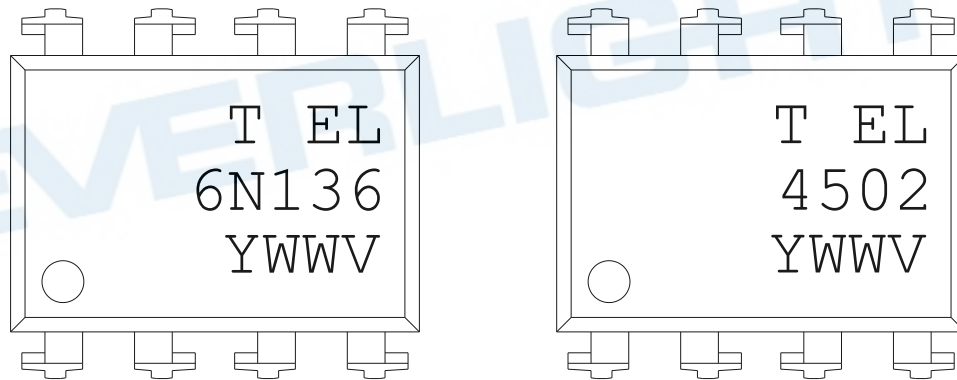


### Notes.

Suggested pad dimension is just for reference only.

Please modify the pad dimension based on individual need.

## Device Marking

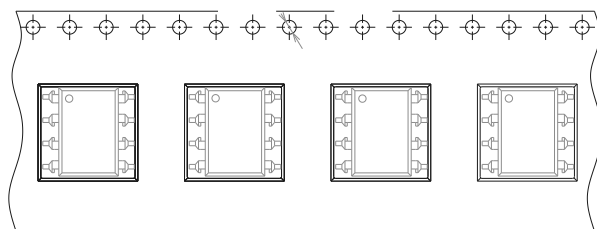


## Notes

T	denotes Factory
	No code : made in China
	T : made in Taiwan
EL	denotes EVERLIGHT
4502	denotes Device Number
6N136	denotes Device Number
Y	denotes 1 digit Year code
WW	denotes 2 digit Week code
V	denotes VDE (optional)

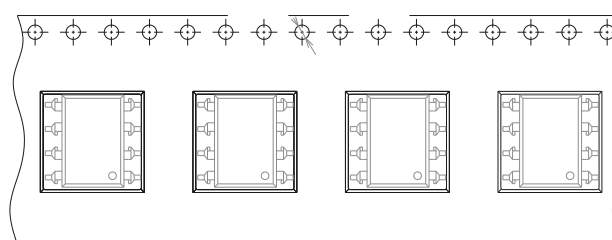
## Tape & Reel Packing Specifications

**Option TA**



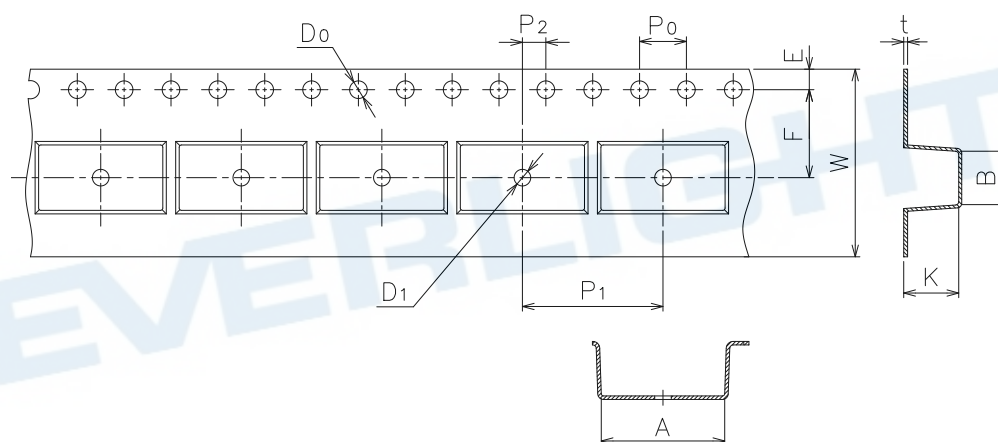
Direction of feed from reel

**Option TB**



Direction of feed from reel

## Tape dimensions

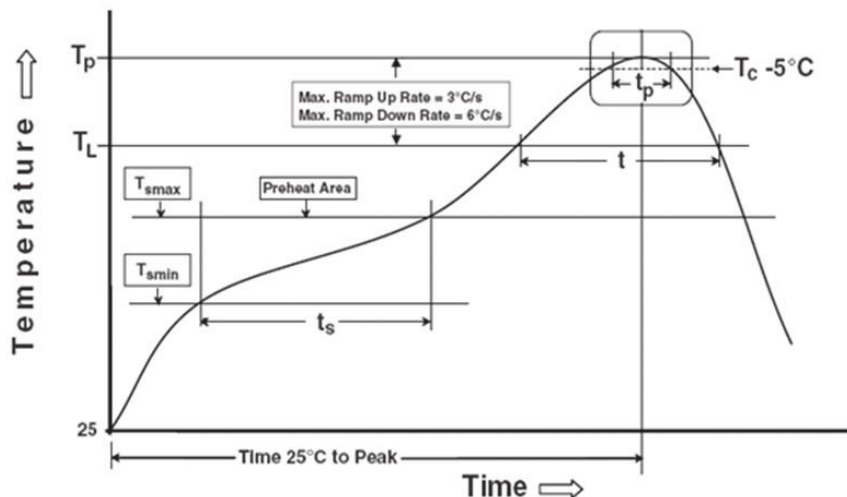


Dimension No.	A	B	Do	D1	E	F
Dimension(mm)	10.4±0.1	10.0±0.1	1.5+0.1/-0	1.5±0.25	1.75±0.1	7.5±0.1
Dimension No.	Po	P1	P2	t	W	K
Dimension(mm)	4.0±0.1	12.0±0.1	2.0±0.05	0.4±0.05	16.0±0.3	4.5±0.1

## Precautions for Use

### 1. Soldering Condition

#### 1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Reference: IPC/JEDEC J-STD-020D

#### Preheat

Temperature min ( $T_{smin}$ )	150 °C
Temperature max ( $T_{smax}$ )	200°C
Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 seconds
Average ramp-up rate ( $T_{smax}$ to $T_P$ )	3 °C/second max

#### Other

Liquidus Temperature ( $T_L$ )	217 °C
Time above Liquidus Temperature ( $t_L$ )	60-100 sec
Peak Temperature ( $T_P$ )	260°C
Time within 5 °C of Actual Peak Temperature: $T_P - 5^\circ\text{C}$	30 s
Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature	8 minutes max.
Reflow times	3 times

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